

1/7/2 (Item 2 from file: 351)
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Flexible substrate for printed circuit - comprises metallic vapour deposited layer formed on surface of plastic film having specified surface tension

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Patent Family:

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JP 1321687	A	19891227	JP 88154387	A	19880622	199007 B

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Patent Details:

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JP 1321687	A	9		

Abstract (Basic): JP 1321687 A

The flexible substrate comprises the metallic vapour deposited layer formed, directly or through resin layer, on the surface of plastics film of which surface tension of at least 54 dyne/cm is given by glow discharge plasma treatment, and the thick metal film layer plated on the metallic vapour deposited layer by electroplating.

Pref. (1) the plastics film comprises films of polyester, polyphenylene sulphide, polyimide, poly parasin acid, polyether sulphone, polyether-ether ketone, aromatic polyamide, polyoxazol, and halogen substd. cpd. and methyl substd. cpd. The metallic vapour deposited layer and the metal layer by electroplating comprise copper, nickel, tin, and their alloys. (3) resistance of the metallic vapour deposited layer is up to 1.0 ohm/cm. (4) Thickness of the metal layer by electroplating is 0.5-30 microns.

USE/ADVANTAGE - The flexible substrate is used for the camera, printer, watch, video and audio devices, computer. Thin metal layer of 0.5-17 micron thickness can be formed on plastics film. Attachment and precision of pattern are improved.

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